

Appl. No. 10/708,783  
Amdt. dated August 9, 2005  
Reply to Office action of April 18, 2005

### REMARKS/ARGUMENTS

1. Claims 1-4, 6, and 7 are rejected under 35 U.S.C. 103(a) as  
being unpatentable over Steffan et al. (U.S. Pat. No. 6338001)  
5 in view of Chen et al. (U.S. Pat. No. 5862055).

Response:

10 Claims 1-4, 6, and 7 have been canceled, and so are no longer in  
need of consideration.

2. Claim 5 is rejected under 35 U.S.C. 103(a) as being  
unpatentable over Steffan et al. (U.S. Pat. No. 6338001) in  
view of Chen et al. (U.S. Pat. No. 5862055), as applied to  
15 Claim 4 above, and further in view of Dor et al. (U.S. Pub.  
No. 20020072162).

Response:

20 Claim 5 has been canceled, and so is no longer in need of  
consideration.

3. **Introduction to new claim 8:**

25 No new matter has been introduced by the new claim 8, and the  
new claim 8 is fully supported by the specification and figures as  
filed (Paragraphs [0017], [0018]).

Claim 8 is added to describe the present application method is

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5 applied for monitoring a machine and product wafers are utilized as  
monitor wafers. The benefit of using product wafers is that problems  
of a monitored machine in the semiconductor process can be  
immediately found out. When a product wafer is selected to be  
inspected, whether a *killer defect generated by the currently machine*  
*(the monitored machine) presents or not can be immediately detected*  
according to the steps of the method of the present application.  
Therefore, if the killer defects generated by the monitored machine  
present, the responsible person of the monitored machine can stop  
10 the machine right now and check for the cause of the killer defect to  
report or solve the problem. Accordingly, the situation that problems  
can only be found out through a *monitor wafer* during a *daily check*  
while lots of product wafers has been running in the machine of the  
prior-art method can be avoided.

15 In contrast to the present application, prior-art methods use bare  
wafers as monitor wafers. In the daily check, bare wafers are used to  
detect for checking the performance of machines. However, when  
killer defects produced by a certain machine are found, hundreds of  
20 wafers have been run in the certain machine and which may all have  
killer defects. Therefore, prior-art methods take a long time to find  
out defects and which machine generates killer defects, and to  
resolve the problems.

25 According to Steffan et al.'s disclosure, a method of  
manufacturing and inspecting semiconductor devices wherein  
defects on inspection wafers are tabulated (abstract). Also, the  
ADC is used to classify kill ratio and calculate die health (col.3,

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lines 32-42). Therefore, the function and purpose of Steffan et al.'s disclosure is for analyzing kill ratio of wafers and measuring yield of wafers and not for monitoring a machine.

5           In addition, according of Chen et al.'s disclosure, they disclose  
a method of determining classification codes for defects occurring  
in semiconductor manufacturing processes and for storing the  
information used to determine the classification codes (abstract). The  
system shown in Fig.3 stores the classification code in the ADC  
10 database as indicated at 310 (col.5, lines 18-25). Therefore, the  
disclosure of Chen et al. is a traditional method for storing ADC  
information database.

15           From the above discussion, neither Steffan et al.'s disclosure  
nor Chen et al.'s disclosure teach a method for monitoring a  
machine by detecting defects of product wafers according to the  
application. Therefore, the applicant believes that the new claim 8  
of the present application is absolutely different from the  
combination of Steffan et al.'s and Chen et al.'s disclosure.  
20 Consideration of the new claim 8 is hereby requested.

4.    **Introduction to new claims 9-13:**

25           No new matter has been introduced by the new claims 9-13, and  
the new claims 9-13 are fully supported by the specification and  
figures as filed.

          Accordingly to claims 9-13, the adoption of product wafer in  
the monitor method can be in conjunction with the ADC, wherein the

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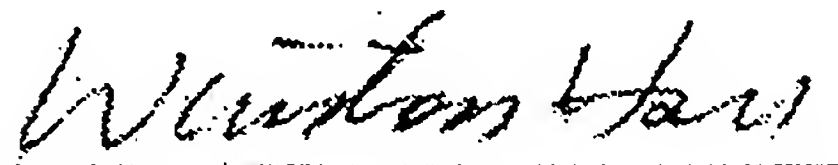
ADC has a database containing possible defect types of each machine or each fabrication process of each layer. Therefore, after detecting defects of the product wafer, pre-layer defects can be separated from the defects generated by the monitored machine according to the database of the ADC, and the defects generated by the monitored machine can be immediately analyzed to determine if the detected defects contains high kill ratio defects or not. If killer defect occurs, the machine is immediately stopped for checking so that the problems of the machine can be solved. Due to the ADC is a non-destructive test, the product wafer is not influenced and can be continuously run in the next fabrication process.

Claims 9-13 are dependent upon the new claim 8 and should be allowed if the new claim 8 is allowed. Consideration of the new claims 9-13 is therefore politely requested.

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

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Sincerely yours,



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Winston Hsu, Patent Agent No. 41,526

5 P.O. BOX 506, Merrifield, VA 22116, U.S.A.

Voice Mail: 302-729-1562

Facsimile: 806-498-6673

e-mail : winstonhsu@naipo.com

- 10 Note: Please leave a message in my voice mail if you need to talk to me. (The time in D.C. is 12 hours behind the Taiwan time, i.e. 9 AM in D.C. = 9 PM in Taiwan.)